

## 20V P-Channel Enhancement Mode MOSFET

### Description

The NP3415EMR uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 1.8V. This device is suitable for use as a load switch or in PWM applications.

### General Features

- ◆  $V_{DS} = -20V$ ,  $I_D = -4A$   
 $R_{DS(ON)}(\text{Typ.}) = 34m\Omega$  @  $V_{GS} = -4.5V$   
 $R_{DS(ON)}(\text{Typ.}) = 44m\Omega$  @  $V_{GS} = -2.5V$
- ◆ High power and current handling capability
- ◆ Lead free product is acquired
- ◆ Surface mount package
- ◆ ESD Rating: 2500V HBM

### Application

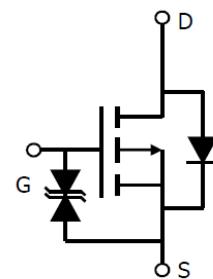
- ◆ PWM applications
- ◆ Load switch

### Package

- ◆ SOT-23-3L

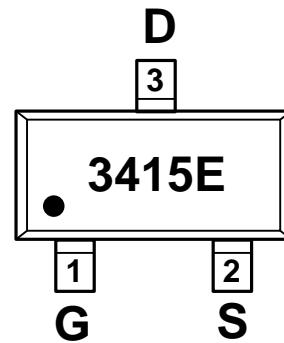


### Schematic diagram



### Marking and pin assignment

SOT-23-3L  
(TOP VIEW)



### Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
NP3415EMR-G	-55°C to +150°C	SOT-23-3L	3000

### Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	$V_{DS}$	-20	V
Gate-source voltage	$V_{GS}$	$\pm 8$	V
Continuous Drain Current	$I_D$	-4	A
		-3	
Pulsed Drain Current <sup>C</sup>	$I_{DM}$	-20	A
Maximum power dissipation <sup>B</sup>	$P_D$	1.4	
		0.9	W
Operating junction Temperature range	$T_j$	-55—150	°C

**Electrical Characteristics** (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>OFF Characteristics</b>						
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-20	-	-	V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V	-	-	-1	μA
Gate-body leakage	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±8V	-	-	±10	μA
<b>ON Characteristics</b>						
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.4	-0.59	-1.2	V
Drain-source on-state resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4A	-	34	60	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-3A	-	44	72	
Forward transconductance	g <sub>f</sub>	V <sub>GS</sub> =-5V, I <sub>D</sub> =-4A	8	-	-	S
<b>Dynamic Characteristics</b>						
Input capacitance	C <sub>ISS</sub>	V <sub>DS</sub> =-10V, V <sub>GS</sub> =0V f=1.0MHz	-	751	-	pF
Output capacitance	C <sub>OSS</sub>		-	115	-	
Reverse transfer capacitance	C <sub>RSS</sub>		-	80	-	
<b>Switching Characteristics</b>						
Turn-on delay time	t <sub>D(ON)</sub>	V <sub>DD</sub> =-10V I <sub>D</sub> =-2.8A V <sub>GEN</sub> =-4.5V R <sub>L</sub> =10ohm R <sub>GEN</sub> =60ohm	-	13	-	ns
Rise time	t <sub>r</sub>		-	9	-	
Turn-off delay time	t <sub>D(OFF)</sub>		-	19	-	
Fall time	t <sub>f</sub>		-	29	-	
Total gate charge	Q <sub>g</sub>	V <sub>DS</sub> =-10V, I <sub>D</sub> =-3A V <sub>GS</sub> =-4.5V	-	9.3	-	nC
Gate-source charge	Q <sub>gs</sub>		-	1	-	
Gate-drain charge	Q <sub>gd</sub>		-	2.2	-	
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>						
Diode forward voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>s</sub> =-1.25A	-	-0.81	-1.2	V

**Thermal Characteristics**

Parameter	Symbol	Typ	Max	Unit
Maximum Junction-to-Ambient <sup>A</sup>	R <sub>θJA</sub>	70	90	°C/W
Maximum Junction-to-Ambient <sup>A D</sup>		100	125	
Maximum Junction-to-Lead <sup>B</sup>		63	80	

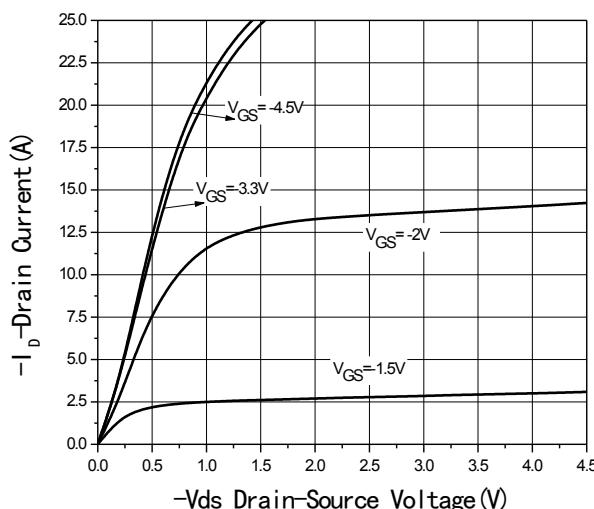
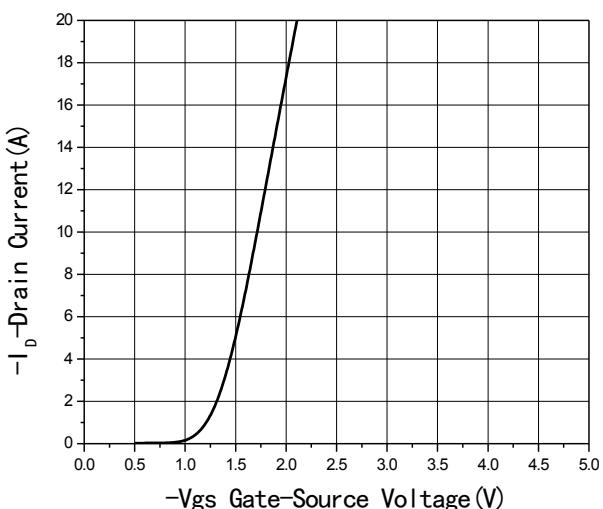
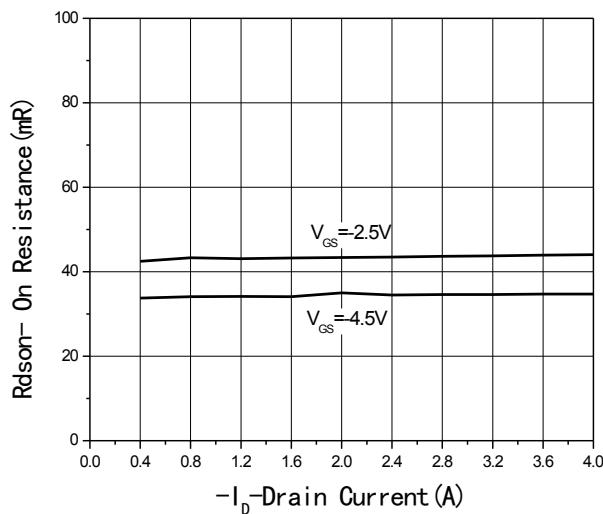
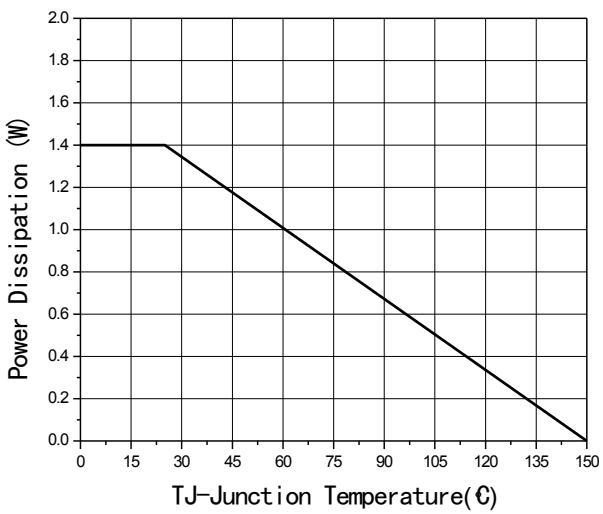
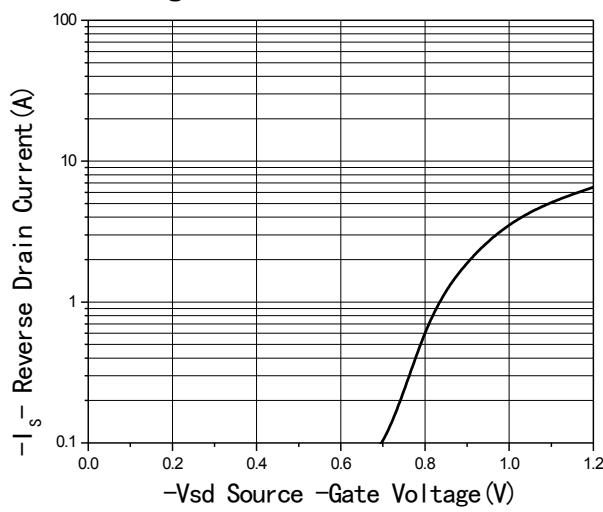
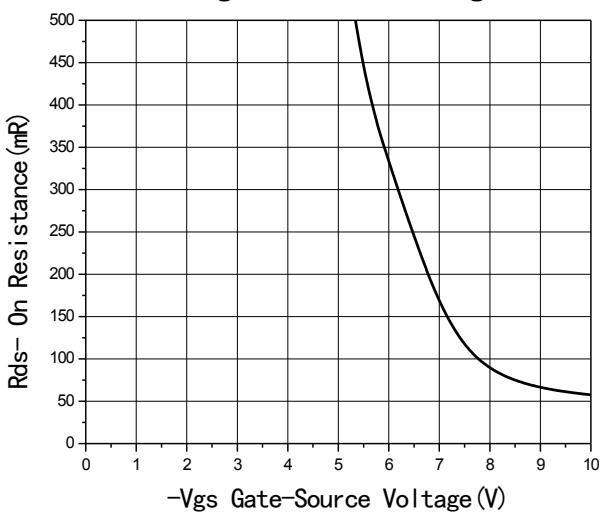
A. The value of R<sub>θJA</sub> is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C. The value in any given application depends on the user's specific board design.

B. The power dissipation P<sub>D</sub> is based on T<sub>J(MAX)</sub>=150°C, using ≤ 10s junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150°C. Ratings are based on low frequency and duty cycles to keep initialTJ=25°C.

D. The R<sub>θJA</sub> is the sum of the thermal impedance from junction to lead R<sub>θJL</sub> and lead to ambient.

**Typical Performance Characteristics**


**Fig1 Output Characteristics**

**Fig2 Transfer Characteristics**

**Fig3 Rdson-Drain current**

**Fig4 Power De-rating**

**Fig5 Source-Drain Diode Forward**

**Fig6 Rdson-Gate Drain voltage**

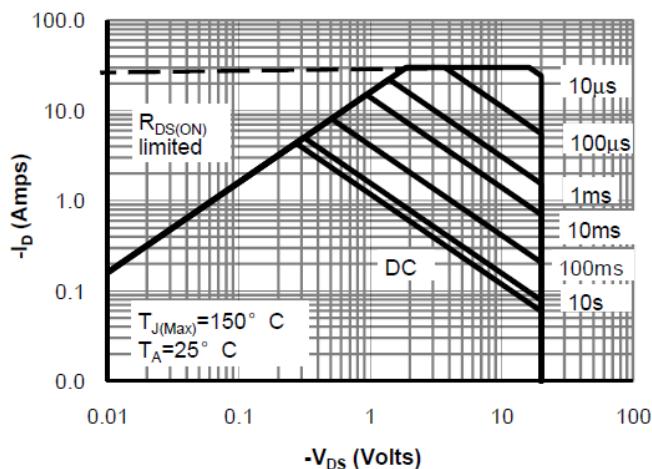


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

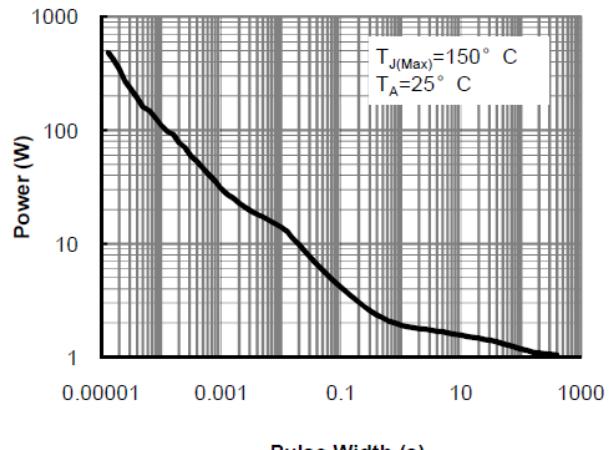


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

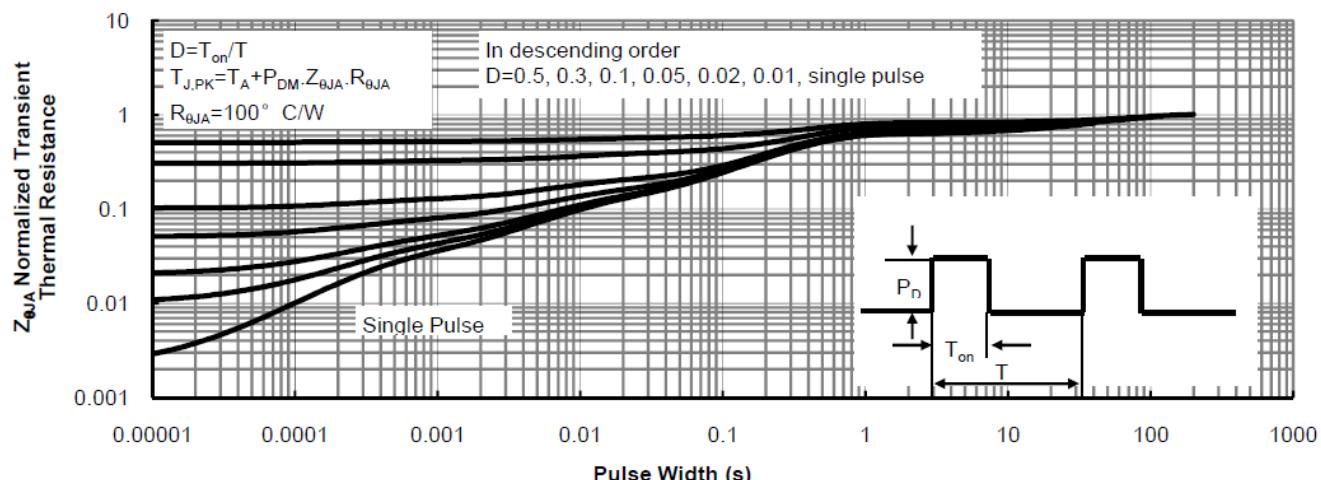
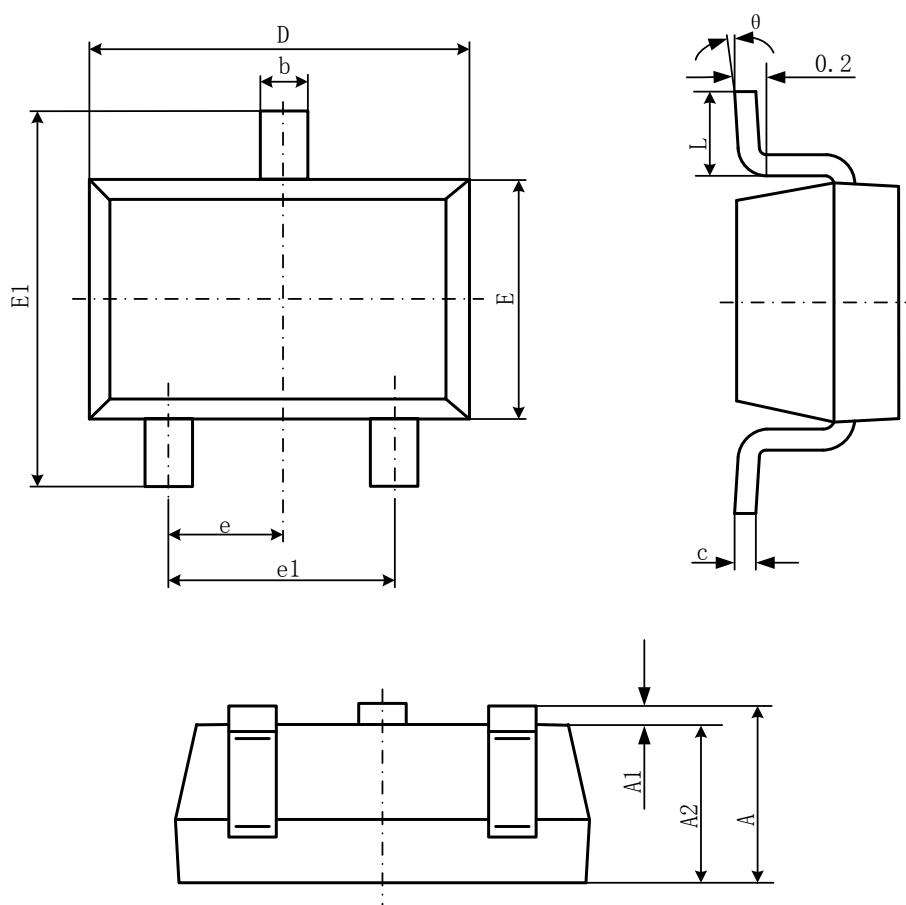


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

## Package Information

- SOT-23-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
$\theta$	$0^\circ$	$8^\circ$	$0^\circ$	$8^\circ$